

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	12	(mems or micro-electro-mechanical system) and spin adj deposit	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:28
S2	1627	(mems or micro-electro-mechanical system) and piezoelectric adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:22
S3	309	(diaphragm or membrane) and S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 10:56
S4	53	rotating and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:00
S5	822	mems and (spin adj coating or spin adj coat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:04
S6	162	precursor and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:01
S7	1	piezoelectric adj film and S6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:01
S8	216	(transducer or diaphragm) and S5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:11
S9	398	(438/50):CCLS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 11:12

S10	318	(mems or micro adj electro adj mechanical adj system or micro-electrical-mechanical-system) and cavity and bonding and piezo	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:35
S11	695	(transducer or sensor) and silicon and (cavity or diaphragm) and piezo and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:36
S12	403	(spin adj coat or spin adj coating or rotating or rotate) and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:37
S13	253	electrode and S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:41
S14	599	(438/53).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 11:46
S15	51	piezo and S14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:46
S16	4	spin and S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 11:46
S17	38151	(mems or micro-electro-mechanical-system)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:23
S18	6930	precursor and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:23
S19	6516	solution and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:23

S20	1934	(spin or rotate or rotating) and S19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:52
S21	114	(microstructure or micro adj structure or micro-structure) and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:51
S22	440	(438/52).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 12:52
S23	122	(spin or rotate or rotating) and S22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 12:53
S24	2505	mems and sealing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 16:44
S25	599	spin and S24	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 16:44
S26	367	silicon and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 16:44